



## Product Change Notification / LIAL-13ERYV184

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**Date:**

18-Jan-2021

**Product Category:**

Memory

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 4198.001 Final Notice: Qualification of ASSH as a new assembly site for selected 24xx01, 24xx02, 24xx04, 24xx08 and 24xx16 device families available in 8L TSSOP package.

**Affected CPNs:**

[LIAL-13ERYV184\\_Affected\\_CPN\\_01182021.pdf](#)  
[LIAL-13ERYV184\\_Affected\\_CPN\\_01182021.csv](#)

**Notification Text:**

**PCN Status:**Final notification.

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:**Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of ASSH as a new assembly site for selected 24xx01, 24xx02, 24xx04, 24xx08 and 24xx16 device families available in 8L TSSOP package.

**Pre Change:**

Assembled at MMT using gold (Au) bond wire, 2200D die attach material, G600V molding compound material, with Matte tin lead plating finish and using lead frame without lead lock

**Post Change:**

Assembled at ASSH using palladium coated copper (PdCu) bond wire, EN-4900GC die attach material, G700LY molding

compound material, with Ru-PPF lead plating finish and using lead frame with lead lock

**Pre and Post Change Summary:**

|                           | Pre Change                                                    | Post Change                                               |
|---------------------------|---------------------------------------------------------------|-----------------------------------------------------------|
| Assembly Site             | Microchip Technology<br>Thailand<br>(MMT)                     | ASE Advanced Semiconductor<br>(Shanghai) Co., Ltd<br>ASSH |
| Wire material             | Au                                                            | PdCu                                                      |
| Die attach material       | 2200D                                                         | EN-4900GC                                                 |
| Molding compound material | G600V                                                         | G700LY                                                    |
| Lead frame material       | C7025                                                         | C7025                                                     |
| Lead Plating Finish       | Matte tin                                                     | Ru-PPF                                                    |
| Lead frame lead-lock      | No                                                            | Yes                                                       |
|                           | See Pre and Post Change attachment for lead frame comparison. |                                                           |

**Impacts to Data Sheet:** None

**Change Impact:**None

**Reason for Change:**To improve on-time delivery performance by qualifying ASSH as a new assembly site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**February 9, 2021 (date code: 2107)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

|                               | January 2021 |    |    |    |    | February 2021 |    |    |    |  |
|-------------------------------|--------------|----|----|----|----|---------------|----|----|----|--|
| Workweek                      | 01           | 02 | 03 | 04 | 05 | 06            | 07 | 08 | 09 |  |
| Qual Report Availability      |              |    |    | X  |    |               |    |    |    |  |
| Final PCN Issue Date          |              |    |    | X  |    |               |    |    |    |  |
| Estimated Implementation Date |              |    |    |    |    |               | X  |    |    |  |

**Method to Identify Change:** Traceability code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:****January 18, 2021:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on February 9, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_LIAL-13ERYV184\\_Qual Report.pdf](#)

[PCN\\_LIAL-13ERYV184\\_Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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